SCES648-FEBRUARY 2006

FEATURES

- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Low Power Consumption, 25-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation

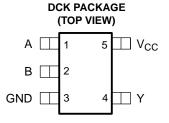
DESCRIPTION/ORDERING INFORMATION

This single 2-input positive-OR gate is designed for 1.65-V to 5.5-V $V_{\rm CC}$ operation.

The SN74LVC1G32-Q1 performs the Boolean function Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

DBV PACKAGE (TOP VIEW) A 1 5 VCC B 2 GND 3 4 Y



See mechanical drawings for dimensions.

ORDERING INFORMATION

T _A	PACKAGE(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING (2)
–40°C to 125°C	SOT (SOT-23) - DBV	Reel of 3000	SN74LVC1G32QDBVRQ1	C32_
-40 C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74LVC1G32QDCKRQ1	CG_

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INP	OUTPUT	
Α	В	Υ
Н	Х	Н
Х	Н	Н
L	L	L

LOGIC DIAGRAM (POSITIVE LOGIC)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74LVC1G32-Q1 SINGLE 2-INPUT POSITIVE-OR GATE





Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	6.5	V	
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high	h-impedance or power-off state (2)	-0.5	6.5	V
Vo	Voltage range applied to any output in the high	h or low state ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current		±50	mA	
	Continuous current through V _{CC} or GND			±100	mA
0	Deckage thermal impedance (4)	DBV package		206	°C/W
θ_{JA}	Package thermal impedance (4)	DCK package		252	°C/VV
		Human-Body Model		2 (H2)	137
	ESD rating ⁽⁵⁾	Charged-Device Model		1 (C5)	kV
		Machine Model		200 (M3)	V
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed. The value of V_{CC} is provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7. ESD protection level per AEC Q100 classification





Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT			
\ /	Complementaria	Operating	1.65	5.5	٧			
V_{CC}	Supply voltage	Data retention only	1.5		V			
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$					
.,	18.11.	V _{CC} = 2.3 V to 2.7 V	1.7		V			
V_{IH}	High-level input voltage	V _{CC} = 3 V to 3.6 V	2		_ v			
		V _{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$					
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$				
\/	Low lovel input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V			
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V			
		V _{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$				
V_{I}	Input voltage		0	5.5	V			
Vo	Output voltage		0	V _{CC}	V			
		V _{CC} = 1.65 V		-4				
		V _{CC} = 2.3 V		-8				
I_{OH}	High-level output current	V _{CC} = 3 V		-16	mA			
				-24				
		V _{CC} = 4.5 V		-32				
		V _{CC} = 1.65 V		4				
		V _{CC} = 2.3 V		8				
I_{OL}	Low-level output current	V _{CC} = 3 V		16	mA			
			24					
		V _{CC} = 4.5 V		32				
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20				
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	10	ns/V				
		$V_{CC} = 5 V \pm 0.5 V$		5				
T _A	Operating free-air temperature	,	-40	125	°C			

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LVC1G32-Q1 SINGLE 2-INPUT POSITIVE-OR GATE





Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

F	PARAMETER TEST CONDITIONS		V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT
		$I_{OH} = -100 \mu A$	1.65 V to 5.5 V	V _{CC} - 0.1	·		
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
\/		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			V
V _{OH}		$I_{OH} = -16 \text{ mA}$	3 V	2.35			V
		$I_{OH} = -24 \text{ mA}$	3 V	2.3			
		$I_{OH} = -32 \text{ mA}$	4.5 V	3.7			
		I _{OL} = 100 μA	1.65 V to 5.5 V		·	0.1	
		I _{OL} = 4 mA	1.65 V			0.45	
\/		I _{OL} = 8 mA	2.3 V			0.4	V
V _{OL}		I _{OL} = 16 mA	3 V			0.5	V
		I _{OL} = 24 mA	3 V			0.65	
		I _{OL} = 32 mA	4.5 V			0.65	
I	I_I A or B inputs $V_I = 5.5 \text{ V or GND}$		0 to 5.5 V			±5	μΑ
l _{off}		V_I or $V_O = 5.5 \text{ V}$	0			±25	μΑ
I_{CC} $V_I = 5$		$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V			25	μΑ
ΔI_{CC}		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500	μΑ
C_{i}	·	$V_I = V_{CC}$ or GND	3.3 V		4		pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM TO (OUTPUT)		V _{CC} = ± 0.	1.8 V 15 V		2.5 V 2 V	V _{CC} = ± 0.	3.3 V .3 V	ν _{cc} : ± 0.		UNIT	
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t _{pd}	A or B	Υ	1.9	11	0.6	7.5	0.9	6.5	0.5	6	ns	

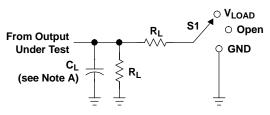
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	V _{CC} = 5 V TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	20	20	21	22	pF



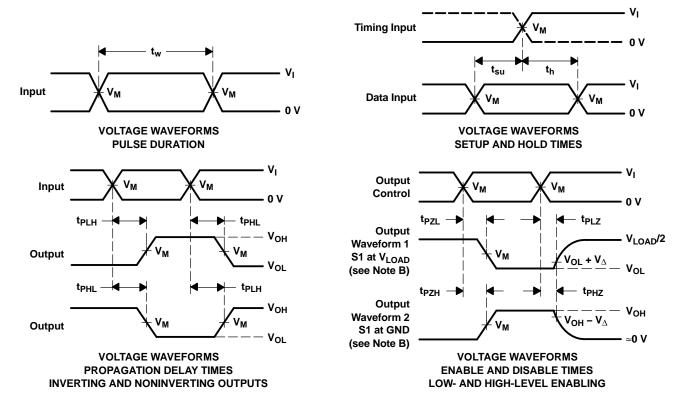
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	INPUTS		.,	V	•	1	V
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R_L	$oldsymbol{V}_{\Delta}$
1.8 V \pm 0.15 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	V _{CC}	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

www.ti.com 8-Jul-2009

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins P	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1G32QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVC1G32-Q1:

Catalog: SN74LVC1G32

Enhanced Product: SN74LVC1G32-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



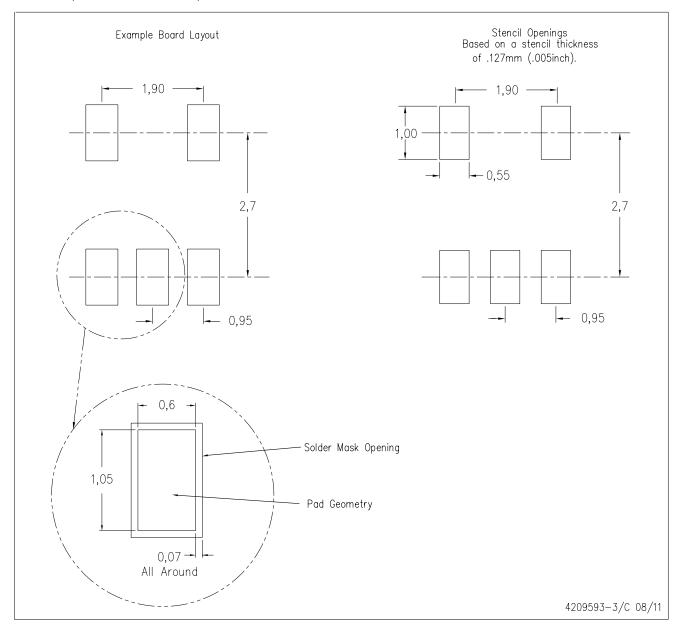
NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



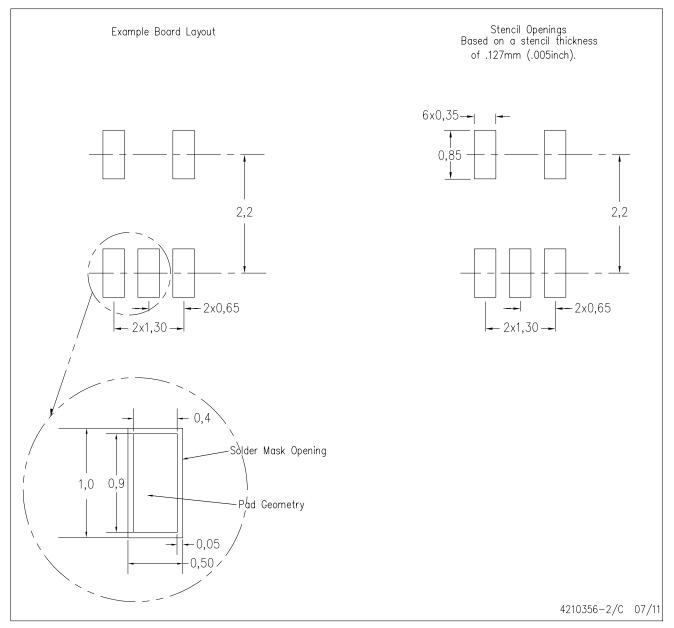
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated

e2e.ti.com

TI E2E Community Home Page